



PATENT
Attorney's Docket No. 1232-4421US1

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: UEHARA et al.

Group Art 1765

Serial No.: 09/664,715

Examiner: Kin Chan Chen

Filed : September 19, 2000

Confirmation 1475

For : WAFER PROCESSING APPARATUS, WAFER PROCESSING METHOD,
AND SEMICONDUCTOR SUBSTRATE FABRICATION METHOD

PRELIMINARY AMENDMENT

BOX RCE
Commissioner for Patents
Washington, D.C. 20231

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APR 03 2002
TC 1700

Sir:

In response to the Notice of Allowance and Notice of Allowability mailed January 9, 2002, Applicants hereby submit the Preliminary Amendment along with a Request for Continued Examination (RCE).

Prior to examination, please enter this Preliminary Amendment and amend the patent application as follows:

IN THE CLAIMS:

Please add claims 40 and 41 as follows:

—40. (New) A semiconductor substrate fabrication method, comprising:

completely dipping a substrate on which a porous layer is exposed into an etching solution; and

removing the porous layer of the substrate with the etching solution while rotating the substrate.

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